



CALL FOR PAPERS – Solgel 2024

The **22nd international Sol-Gel conference** will bring together experts in the fields of inorganic and organic-inorganic hybrid materials prepared by sol-gel and related soft chemistry routes. It will be the place to cross the frontiers between academy and industry, and will cover all aspects of materials and nanomaterials design from fundamentals to applications.

The **international Sol-Gel conference** is a gathering with the following objectives:

- Attract high quality papers in different subfields
- Offer the opportunity to be updated on the latest research outputs on several topics
- Organize specific workshops around the most attractive and current issues
- Gather worldwide experts as conference speakers

Topics of interest include, but are not limited to:

- Chemistry and fundamentals of the sol-gel process
- Organic-inorganic hybrid materials
- Nano- and micro-structured materials
- Porous materials and hierarchical structured materials
- Bio and bioinspired materials
- Protective functional coatings and thin films
- Characterization and modelling techniques for sol-gel materials
- Sol-Gel materials for (photo-)catalysis and membranes
- Sol-Gel materials for energy and environmental applications
- Sol-Gel materials for health and medical applications
- Sol-Gel materials for electronic, magnetic and ferroelectric applications
- Sol-Gel materials for sensors, optic, photonic and optoelectronic applications
- Industrialization of sol-gel science and technology

Important Dates:

- Early bird submission deadline: November 30th, 2023
- Early bird registration deadline: December 31st, 2023
- Regular submission deadline: February 28th, 2024
- Notification to authors: April 15th, 2024
- Regular registration deadline: June 21st, 2024
- Conference: September 1st-6th, 2024

Guidance for authors:

The submission must be done through our submission platform (<https://solgel2024.exordo.com/>) where you will have to create your own account. This abstract management system will enable you to manage your submission as you wish.

Proceedings & Publishing:

More information coming soon.